56 OE4

55 8B1

54 ¶8B2

53 GND

52 ¶8B3

51 8B4

50 VCC

49 ∏8A

48 7B1

47 **∏** 7B2

46 GND

45 🛮 7B3

35 V<sub>CC</sub>

34 🛮 5B1

DGG, DGV, OR DL PACKAGE

(TOP VIEW)

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- **Member of the Texas Instruments** Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Output Ports Have Equivalent 26- $\Omega$  Series Resistors, So No External Resistors Are Required
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DGG), Thin Shrink Small-Outline (DL), and Thin Very Small-Outline (DGV) Packages

NOTE: For tape and reel order entry: The DGGR package is abbreviated to GR, and the DGVR package is abbreviated to VR.

#### description

This 1-bit to 4-bit address driver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74ALVCH162344 is used in applications in which four separate memory locations must be addressed by a single address.

The outputs, which are designed to sink up to 12 mA, include equivalent 26- $\Omega$  resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, the output enable  $(\overline{OE})$  inputs should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

2B4 | 13 44**∏**7B4 2A 🛮 14 43 7A 42 🛮 6A 3A 🛮 15 3B1 **1**16 41 ¶ 6B1 3B2 [] 17 40 **∏** 6B2 GND ∏18 39 | GND 3B3 **∏** 19 38 **∏** 6B3 3B4 🛮 20 37 6B4 4A 🛮 21 36 🛮 5A

V<sub>CC</sub> 1 22

4B1 **[**] 23

OE1

1B1 **1**2

1B2 **∏**3

GND []4

1B3 🛮 5

1B4 **[**] 6

V<sub>CC</sub> **□**7

1A 🛮 8

2B1 🛮 9

2B2 110

GND [] 11

2B3 🛮 12

4B2 🛮 24 33 5B2 GND II 25 32 I GND 4B3 🛮 26 31 5B3 4B4 **[**] 27 30 5B4 OE2 **1**28 29 OE3

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH162344 is characterized for operation from -40°C to 85°C.

#### A-TO-B FUNCTION TABLE

INPUTS		OUTPUT
OE	Α	Bn
L	Н	Н
L	L	L
Н	Χ	Z

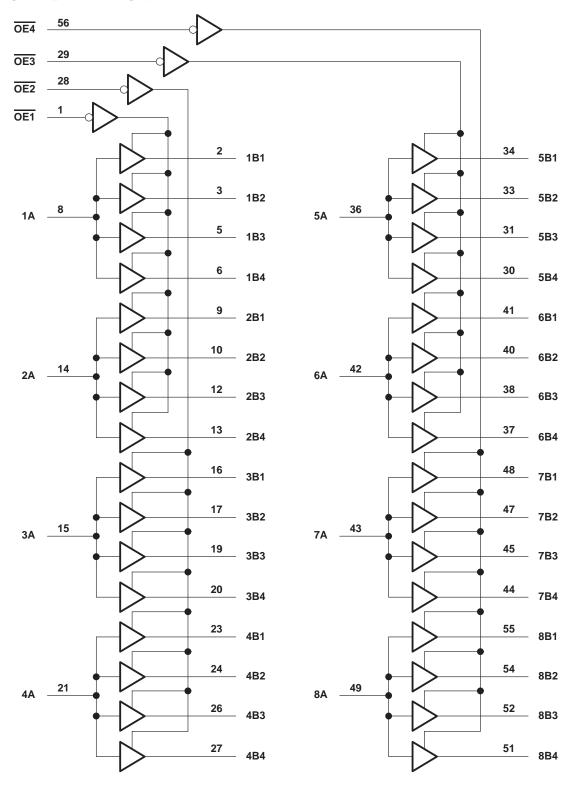


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### logic diagram (positive logic)





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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (see Note 1)	
Output voltage range, VO (see Notes 1 and 2)	0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–50 mA
Output clamp current, IOK (VO < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG pack	age 81°C/W
DGV packa	age 86°C/W
DL packag	e
Storage temperature range, T <sub>stq</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		1.65	3.6	V	
VIH		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>		T	
	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
V <sub>IL</sub>		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		0.35 × V <sub>CC</sub>		
	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	VCC	V	
٧o	Output voltage		0	VCC	V	
		V <sub>CC</sub> = 1.65 V		-2		
la	High-level output current	V <sub>CC</sub> = 2.3 V		-6	^	
ЮН		V <sub>CC</sub> = 2.7 V		-8	mA	
		V <sub>CC</sub> = 3 V		-12		
		V <sub>CC</sub> = 1.65 V	2			
lOL	Low-level output current	V <sub>CC</sub> = 2.3 V		6	mA	
		V <sub>CC</sub> = 2.7 V		8		
		V <sub>CC</sub> = 3 V		12		
Δt/Δν	Input transition rise or fall rate			10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CONDITIONS	Vcc	MIN TYP1	MAX	UNIT	
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2			
		$I_{OH} = -2 \text{ mA}$	1.65 V	1.2			
		$I_{OH} = -4 \text{ mA}$	2.3 V	1.9			
Vон		Lav. CmA	2.3 V	1.7		V	
		IOH = -6  mA	3 V	2.4			
		$I_{OH} = -8 \text{ mA}$	2.7 V	2			
		I <sub>OH</sub> = -12 mA	3 V	2			
		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V		0.2		
		I <sub>OL</sub> = 2 mA	1.65 V		0.45		
		I <sub>OL</sub> = 4 mA	2.3 V		0.4		
VOL		la. 6 mA	2.3 V		0.55	V	
		IOL = 6 mA	3 V		0.55		
		I <sub>OL</sub> = 8 mA	2.7 V		0.6		
		I <sub>OL</sub> = 12 mA	3 V		0.8		
lį		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V		±5	μΑ	
		V <sub>I</sub> = 0.58 V	1.65 V	25			
		V <sub>I</sub> = 1.07 V	1.65 V	-25			
		V <sub>I</sub> = 0.7 V	2.3 V	45			
I <sub>I</sub> (hold)		V <sub>I</sub> = 1.7 V	2.3 V	<del>-4</del> 5		μΑ	
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V	3 V	<b>-</b> 75			
		$V_1 = 0 \text{ to } 3.6 \text{ V}^{\ddagger}$	3.6 V		±500		
loz		$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ	
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ	
ΔlCC		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V		750	μΑ	
Ci	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	2.5	;	pF	
	Data inputs	Al = ACC OLOUD		3.5	;	pΓ	
Co	Outputs	$V_O = V_{CC}$ or GND	3.3 V	4		pF	

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

### switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	А	В	§	1	4.9		5.1	1.4	4.4	ns
<sup>t</sup> en	ŌĒ	В	§	1	6.4		6.6	1.2	5.7	ns
<sup>t</sup> dis	ŌĒ	В	§	1	5.4		4.7	1.2	4.5	ns
t <sub>sk(o)</sub> ¶									0.35	ns
tsk(o)#									0.5	ns

<sup>§</sup> This information was not available at the time of publication.

<sup>#</sup> Skew between outputs of all banks of same package (A1–A8 tied together)



<sup>‡</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

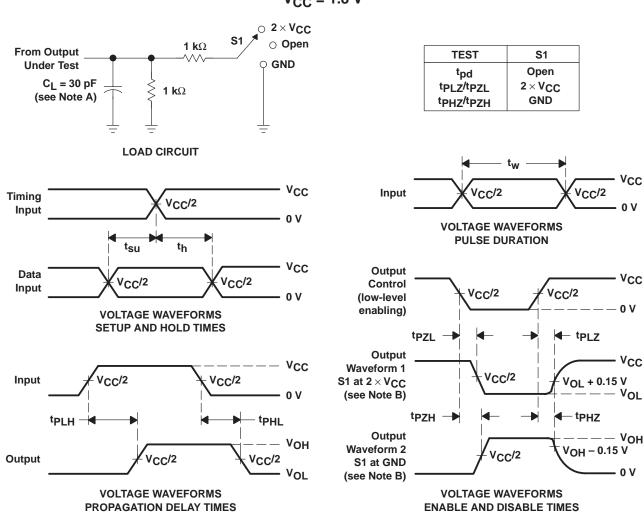
<sup>¶</sup> Skew between outputs of the same bank and same package (same transition)

### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT	
		TEST CONDITIONS	TYP	TYP	TYP		
C <sub>pd</sub> Power dissipation capacitance	Outputs enabled	C <sub>L</sub> = 0, f = 10 MHz	†	68	82	pF	
	Outputs disabled		†	12	14		

<sup>†</sup> This information was not available at the time of publication.

## PARAMETER MEASUREMENT INFORMATION V<sub>CC</sub> = 1.8 V

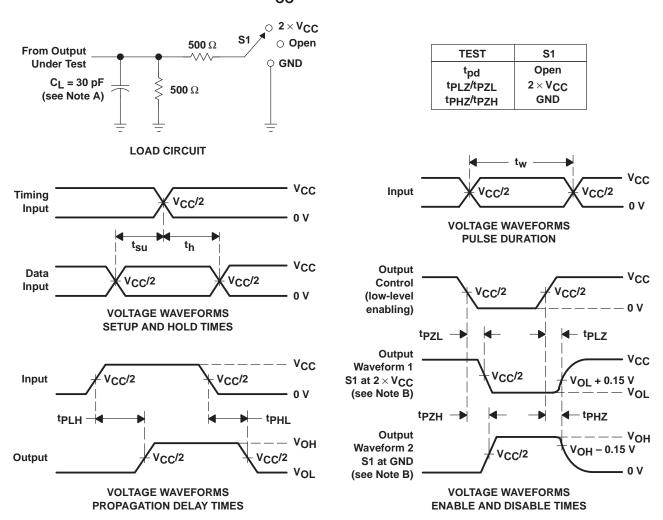


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z  $_{\mbox{O}}$  = 50  $\Omega$ ,  $t_{\mbox{f}}$   $\leq$  2 ns,  $t_{\mbox{f}}$   $\leq$  2 ns,
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLZ and tpHZ are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



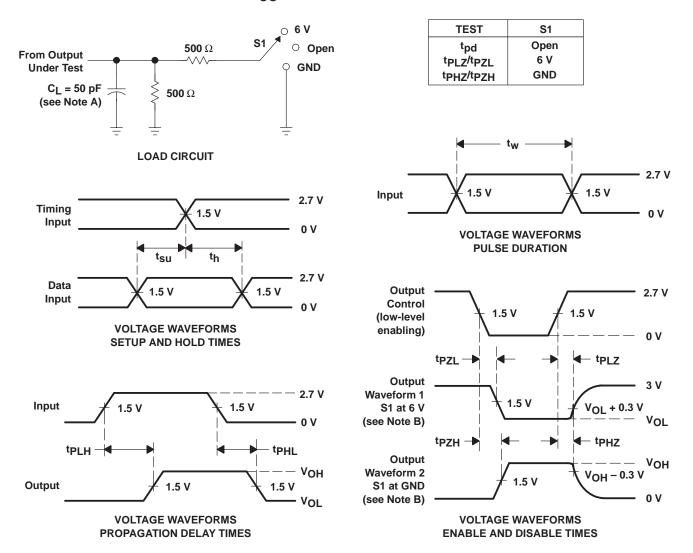
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2$  ns.  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7 \text{ V}$ AND 3.3 V $\pm$ 0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq 2.5$  ns.  $t_f \leq 2.5$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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